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Applicant: Hunt Hang Jiang, et al.  
Confirmation No.: 4925  
Serial No.: 09/834,273  
Filed: April 12, 2001  
For: STRUCTURE AND METHOD  
FOR DEPOSITING SOLDER  
BUMPS ON A WAFER  
  
Art Group Unit: 2823  
Examiner: Deven M. Collins  
Attorney Docket: 25916-194 (6136/53945)

**CERTIFICATE OF  
MAILING/TRANSMISSION  
(37 C.F.R. § 1.8A)**

I hereby certify that this correspondence is, on  
the date shown below, being:

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Trademark Office

August 5, 2002

  
DIANA R. CASTILLO

**RESPONSE TO RESTRICTION REQUIREMENT**

Commissioner for Patents  
Washington, D.C. 20231

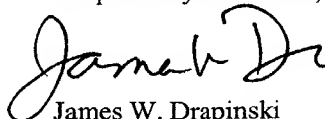
Dear Sir:

This is in response to the Restriction Requirement mailed on June 3, 2002. This response is  
timely with the automatic entry of the accompanying Petition for Extension of time.

Applicants elect Claims 1-12, 20-27, and 35-36 (Group II) for prosecution in this application  
without traverse.

The Commissioner is hereby authorized to charge any additional fees which may be required in  
this application under 37 C.F.R. §§1.16-1.17 or credit any overpayment, to Deposit Account No. 13-0201.  
Should no proper payment be enclosed herewith, as by a check being in the wrong amount, unsigned, post-  
dated, otherwise improper or informal or even entirely missing, the Commissioner is authorized to charge the  
unpaid amount to Deposit Account No. 13-0201. This sheet is filed in duplicate.

Respectfully submitted,

  
James W. Drapinski  
Registration No. 46,242

August 5, 2002  
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